

Bidirectional Single Line TVS Protection Diode UM5060 SOD523

General Description

The UM5060 TVS protection diode is designed to replace multilayer varistors (MLVs) in portable applications such as cell phones, notebook computers, and PDA's. They feature large cross-sectional area junctions for conducting high transient currents, offer desirable electrical characteristics for board level protection, such as fast response time, lower operating voltage, lower clamping voltage and no device degradation when compared to MLVs. The UM5060 TVS protection diode protects sensitive semiconductor components from damage or upset due to electrostatic discharge (ESD) and other voltage induced transient events. The UM5060 is available in SOD523 package with working voltages of 5 volt. It gives designer the flexibility to protect bidirectional single line in applications where arrays are not practical. Additionally, it may be "sprinkled" around the board in applications where board space is at a premium. It may be used to meet the ESD immunity requirements of IEC $61000-4-2, \pm 30$ kV contact discharge.

Applications

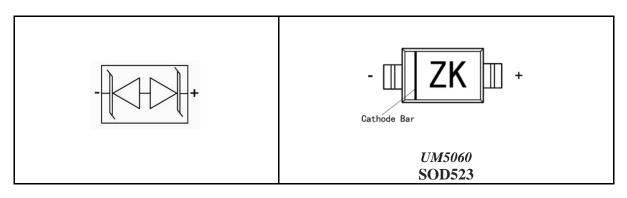
Cell Phone Handsets and Accessories Personal Digital Assistants (PDA's) Notebooks, Desktops and Servers Portable Instrumentation Cordless Phones Smart Card Digital Cameras MP3 Players

Features

Transient protection for data lines to IEC 61000-4-2 (ESD) ±30kV (air), ±30kV (contact) Small package for use in portable electronics Suitable replacement for MLV's in ESD protection applications Bidirectional TVS protection Stand off voltages: 5V Low leakage current Low diode capacitance

Pin Configurations

Top View





Ordering Information

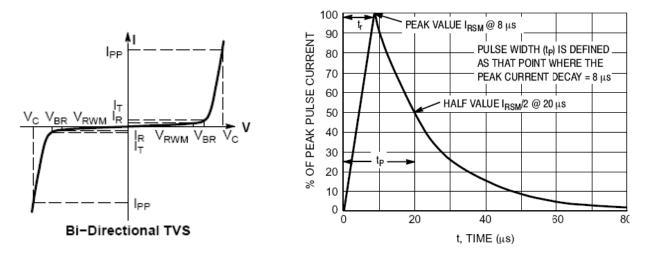
Part Number	Working Voltage	Packaging Type	Channel	Marking Code	Shipping Qty
UM5060	5.0V	SOD523	1	ZK	3000/7 Inch Tape & Reel

Absolute Maximum Ratings

RATING	SYMBOL	VALUE	UNITS
Peak Pulse Power (tp = $8/20\mu s$)	P _{PK}	140	Watts
Maximum Peak Pulse Current (t=8/20µs)	I_{PP}	11	Amps
Lead Soldering Temperature	T _L	260 (10 sec.)	°C
Operating Temperature	T _J	-55 to +125	°C
Storage Temperature	T _{STG}	-55 to +150	°C

Symbol Definition

PARAMETER	SYMBOL
Maximum Reverse Peak Pulse Current	I_{PP}
Clamping Voltage @ Ipp	V _C
Working Peak Reverse Voltage	V_{RWM}
Maximum Reverse Leakage Current @ V _{RWM}	I_R
Breakdown Voltage @ I _T	V_{BR}
Test Current	I _T
Peak Power Dissipation	P _{PK}
Max. Capacitance @ $V_R = 0V$, f = 1MHz	CJ



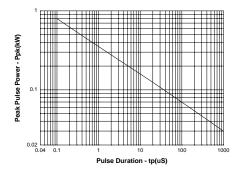


PARAMETER	SYMBOL	CONDITIONS	MIN	ТҮР	MAX	UNIT
Reverse Stand-Off Voltage	V _{RWM}				5	V
Reverse Breakdown Voltage	V _{BR}	$I_T = 1 mA$	6.5		8.5	V
Reverse Leakage Current	I _R	$V_{RWM} = 5V, T=25^{\circ}C$			1	μΑ
Clamping Voltage	V	$I_{PP} = 5A, t_p = 8/20\mu S$			9.7	V
Clamping Voltage	V _C	$I_{PP} = 11A, t_p = 8/20\mu S$			13.6	v
Junction Capacitance	C _J	$V_R = 0V, f = 1MHz$		40	55	pF
Junction Capacitance	CJ	$V_R = 2.5V, f = 1MHz$		30	40	pF

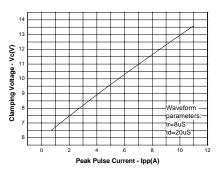
Electrical Characteristics (T=25°C, Device for 5.0V Reverse Stand-off Voltage)

Typical Operating Characteristics

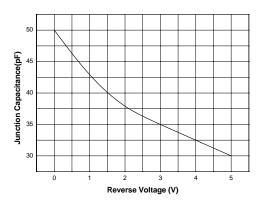
Non-Repetitive Peak Pulse Power vs. Pulse Time



Clamping Voltage vs. Peak Pulse Current



Junction Capacitance vs. Reverse Voltage



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Applications Information

Device Connection Options

UM5060 ESD protection diode is designed to protect one bidirectional data, I/O or power supply line from the damage caused by ESD and surge pulses. The device is bidirectional and may be used on lines where the signal polarity is above ground and below ground.

Circuit Board Layout Recommendations for Suppression of ESD

Good circuit board layout is critical for the suppression of ESD induced transients. The following guidelines are recommended:

- 1. Place the TVS near the input terminals or connectors to restrict transient coupling.
- 2. Minimize the path length between the TVS and the protected line.
- 3. Minimize all conductive loops including power and ground loops.
- 4. The ESD transient return path to ground should be kept as short as possible.
- 5. Never run critical signals near board edges.
- 6. Use ground planes whenever possible. For multilayer printed-circuit boards, use ground vias.
- 7. Keep parallel signal paths to a minimum.
- 8. Avoid running protection conductors in parallel with unprotected conductor.
- 9. Avoid using shared transient return paths to a common ground point.

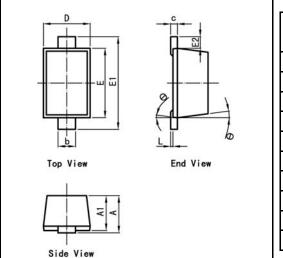




Package Information

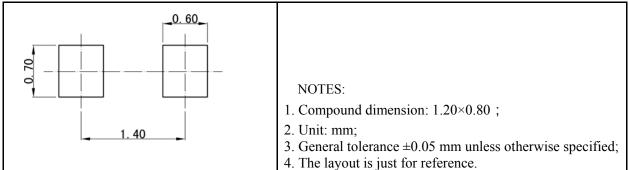
UM5060 SOD523

Outline Drawing

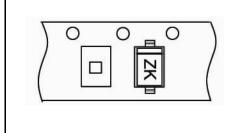


Symbol	millimeters		Inches		
	Min	Max	Min	Max	
А	0.510	0.770	0.020	0.031	
A1	0.500	0.700	0.020	0.028	
b	0.250	0.350	0.010	0.014	
с	0.080	0.150	0.003	0.006	
D	0.750	0.850	0.030	0.033	
Е	1.100	1.300	0.043	0.051	
E1	1.500	1.700	0.059	0.067	
E2	0. 200REF		0.00	8REF	
L	0.010	0.070	0.001	0.003	
θ	7° REF		7° REF		

Land Pattern



Tape and Reel Orientation





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Union Semiconductor, Inc Add: 7F, No. 5, Bibo Road, Shanghai 201203 Tel: 021-51097928 Fax: 021-51026018 Website: www.union-ic.com

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